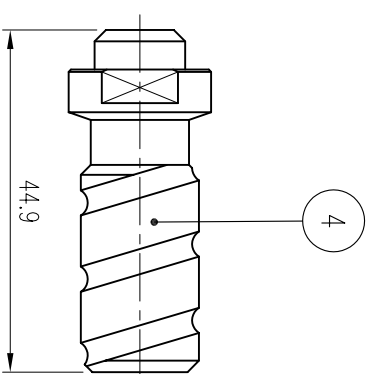
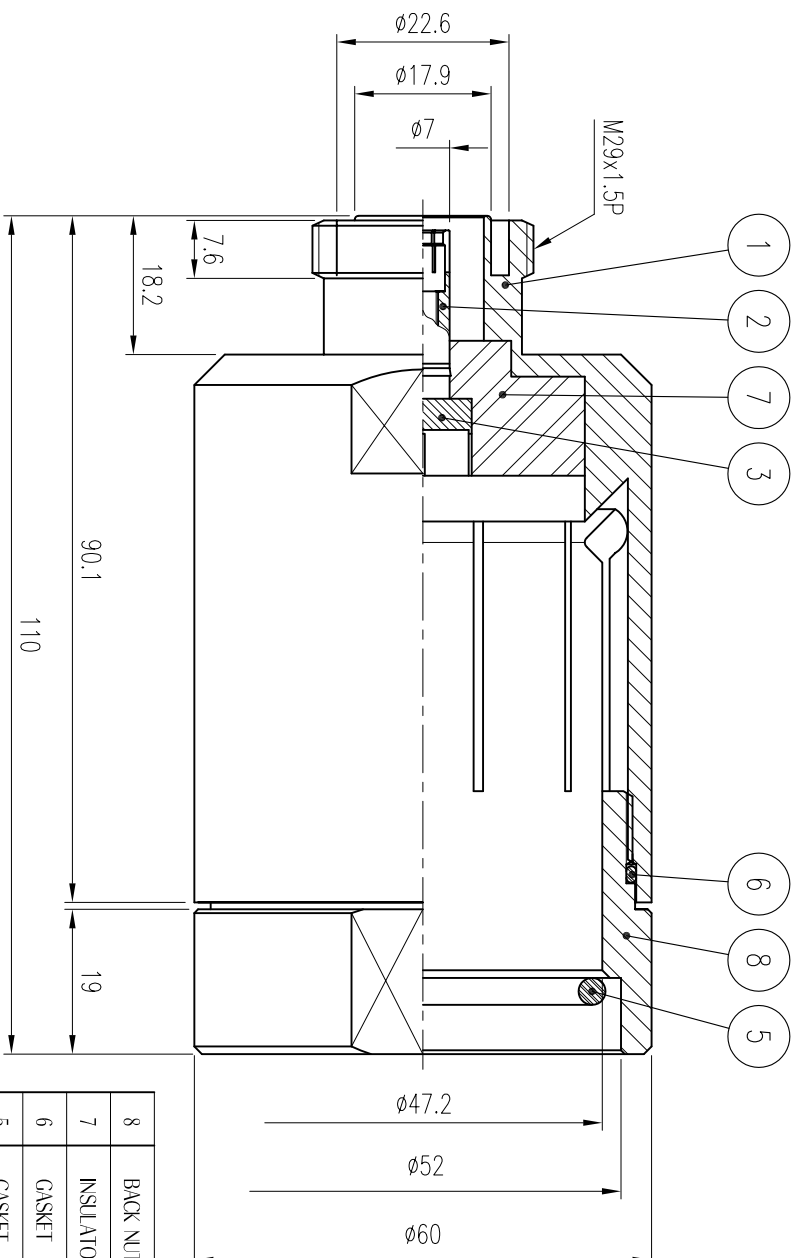


[illegible]

8	BACK NUT	1	MBSD	Silver Plate	DBX000119-5/1 (P5010)
7	INSULATOR	1	TEFLON		DN01042-N/1 (H5064)
6	GASKET	1	SILICONE		DK000119-N/1 (G5018)
5	GASKET	1	SILICONE		DK000118-N/1 (G5017)
4	CONTACT	1	MBSD	Silver Plate	DC101110-5/1 (E5078)
3	CONTACT	1	MBSD	Silver Plate	DC101124-5/1 (E5077)
2	CONTACT	1	BcCu	Silver Plate	DC101123-5/1 (E5076)
1	BODY	1	MBSD	Silver Plate	DBD01474-5/1 (D5076)

인체기능재질		폼변		폼 명		수량	재 질	표면처리	비 고
공동공재 * ±0.1 ** ±0.05	재질 _____ _____ _____	년월일		2002. 5. 3.			 KJ COMTECH TECHNOLOGY KJ COMTECH CO.,LTD. RF & MICROWAVE TECHNOLOGY Tel : 82-25-91-8015 Fax : 82-25-91-8017	7/16 DIN50 CABLE JS 1+5/8"	도면
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		검도							
		제도							
열처리	작성부서	인 구 소					A4	도면	C000580-7/1
보호패막처리		작도	NS	단위	mm	총량			
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